Special Issue

Innovations in 3D Printing 2.0

Message from the Guest Editor

Three-dimensional printing has been growing aggressively, and diverse thought leaders agree that additive manufacturing technology will cause a new industrial revolution, fundamentally changing the way products are made. In addition, the open-source selfreplicating rapid prototyper project has created a tidal wave of innovation from hundreds of developers working together over the web. Enabled by 3-D printing, this allows for the efficient manufacture of geometrically and functionally complex products within a single process step, which provides enormous opportunities for more efficient product design, custom products, and rapid innovation in the product cycle. Three-dimensional printing also holds the potential for advances in global value chains, as well as manufacturing sustainability, including reduced energy consumption, increased materials efficiency, localized production, and increased opportunities for repair and life cycle upgrading. These opportunities will only be realized with continued invention and innovation. That is why I invite you to submit an article for Inventions for this Special Issue entitled Innovations in 3-D Printing.

Guest Editor

Prof. Dr. Joshua M. Pearce

Department of Electrical & Computer Engineering, Western University, London, ON N6A 3K7, Canada

Deadline for manuscript submissions

closed (15 January 2023)



Inventions

an Open Access Journal by MDPI

Impact Factor 1.9 CiteScore 4.9



mdpi.com/si/103807

Inventions
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
inventions@mdpi.com

mdpi.com/journal/inventions





Inventions

an Open Access Journal by MDPI

Impact Factor 1.9 CiteScore 4.9





About the Journal

Message from the Editorial Board

The unique journal *Inventions* is different from all other journals. Many scholars spend their lives publishing research papers in many different journals, but most of these journals do not help scholars collate and analyze their results or assist in promoting them to a relevant industry. However, *Inventions* will help authors not only to publish their papers in the journal, but also to promote their research results to industry and assist them in realizing the purpose of technology transfer. In the future, *Inventions* will help authors to evaluate their technology license fees based on the valuation theory and approaches and also help authors to show their patents and technologies on a network transaction platform.

Editors-in-Chief

Prof. Dr. Chien-Hung Liu

Department of Mechanical Engineering, National Chung Hsing University, 250 Kuo Kuang Rd., Taichung 402, Taiwan

Prof. Dr. Shoou-Jinn Chang

Department of Electrical Engineering, National Cheng Kung University, Tainan 701, Taiwan

Author Benefits

High Visibility:

indexed within Scopus, ESCI (Web of Science), Inspec, Ei Compendex and other databases.

Journal Rank:

JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)

Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 21.8 days after submission; acceptance to publication is undertaken in 2.9 days (median values for papers published in this journal in the first half of 2025).